

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S31	732	semiconductor and ((base or frame or substrate) same ((groove or recess or cavity) with adhesion))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/21 18:34
S32	1459	semiconductor and ((encapsul\$6 or resin) same (((base or frame or substrate) with (metal or copper or cu or Al or aluminum or conductive)) with (groove or wing or cavity or recess\$3))) and @ad<"20040129"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/21 18:37
S33	1113	(257/432-434).ccls. and ((base or frame or substrate) with (metal or copper or cu or Al or aluminum or conductive))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/21 19:12
S34	118	(257/678 or 257/680).ccls. and ((base or frame or substrate) with (metal or copper or cu or Al or aluminum or conductive)) and ((encapsul\$5 or resin) with (transparent or translucent))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/21 19:15
S35	361	(257/796).ccls. and ((base or frame or substrate) with (metal or copper or cu or Al or aluminum or conductive)) and (encapsul\$5 or resin)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/21 20:24